



HEATPIPE [Referred by Heatpipe Sequence Number](#)

PICTURE	NAME	FOR CASE	FOR MAINBOARD
---------	------	----------	---------------



HP1

GA-L01, GD-L01, GS-L01
GS-L02, GS-L02L

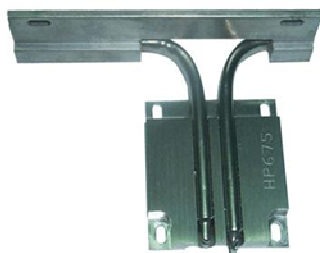
VIA SP & M & PD M/B



HP2

GA-L01

PWI-8552M/B



HP3=HP675

GA-L01, GD-L01, GS-L02,
GS-L02L

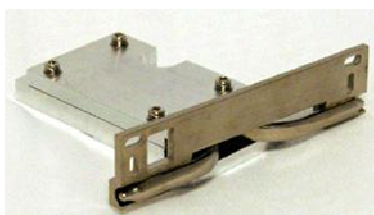
COMELL LV-675 M/B



HP5

GS-L05

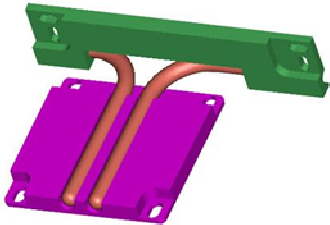
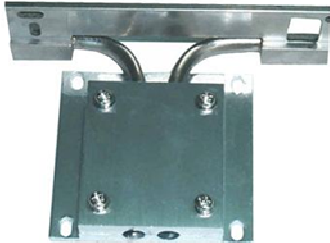
PWI-8552M/B

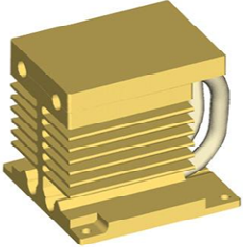
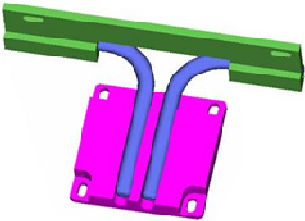
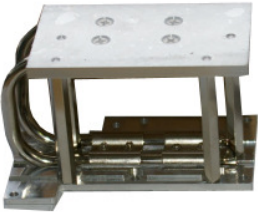


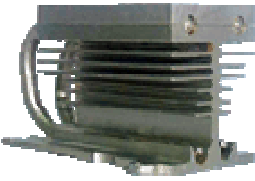
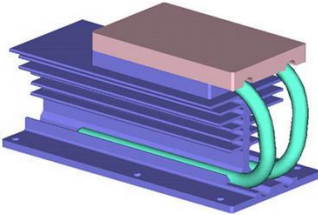
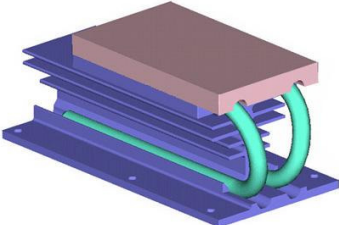
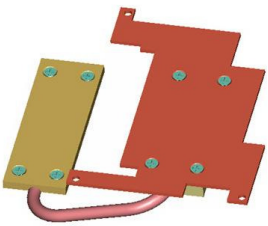
HP6

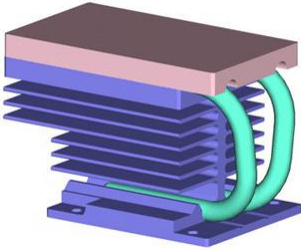
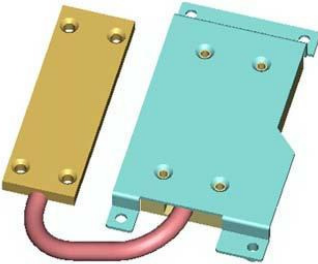
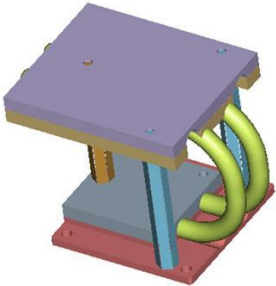
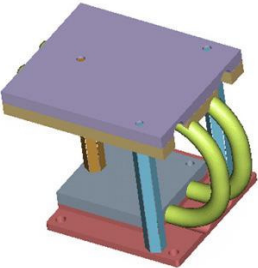
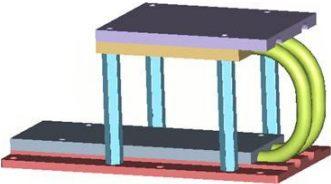
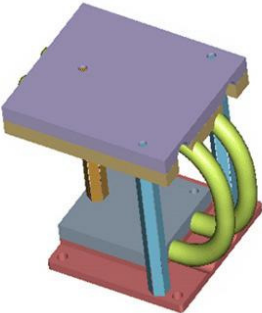
GA-L01, GD-L01, GS-L01,
GS-L02, GS-L02L

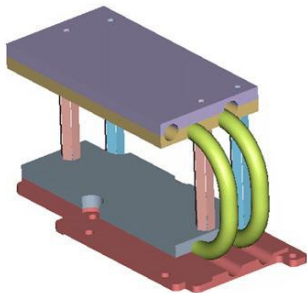
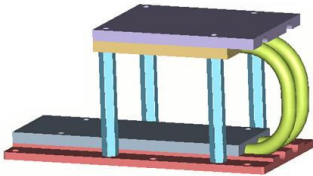
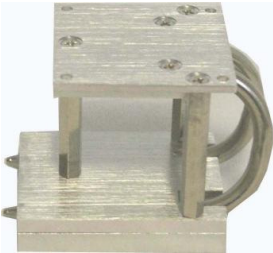
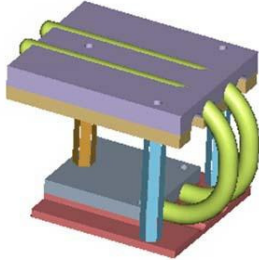
VIA SP & M & PD M/B

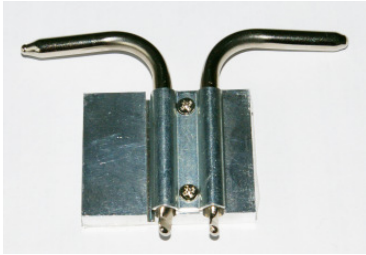
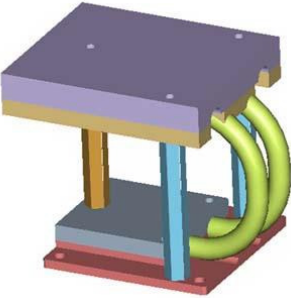
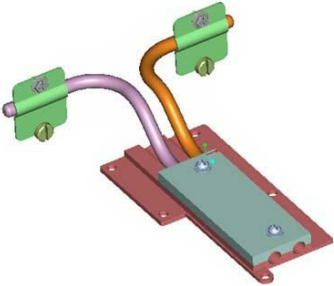
PICTURE	NAME	FOR CASE	FOR MAINBOARD
	HP7	GA-L01, GD-L01, GS-L01 GS-L02, GS-L02L	VIA EN & CN M/B
	HP8	GN-L01	VIA NANO NL M/B
	HP9	GS-L05	IBASE MB879, MB890 & MB896F M/B; Commell LV-675 & LV-677 M/B; VIA VB6002 M/B (PN)
	HP10	GA-L01, GD-L01	EPOX 4MTS6B M/B
	HP12	GA-L01	PWI-8552M/B

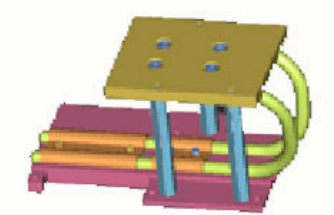
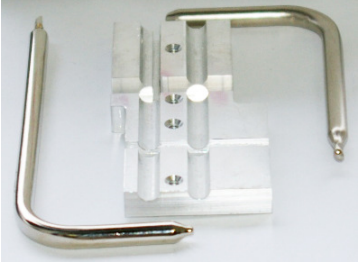
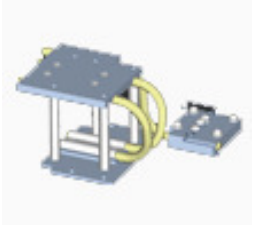
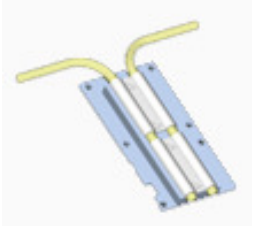
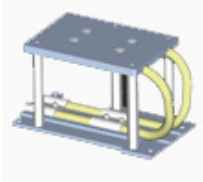
PICTURE	NAME	FOR CASE	FOR MAINBOARD
	HP14	GS-L06	IBASE MB879, MB890, MB896F & MB899 M/B; Commell LV-675 & LV-677 M/B; VIA VB6002 M/B
	HP15	GS-L06	PWI-8552 M/B
	HP16	GA-L01,GD-L01,GS-L01, GS- L02,GS-L02L	VIA VB6002 M/B
	HP18	GS-L05	VIA EK M/B
	HP19	GS-L05	JETWAY WITH C7 CPU M/B
	HP20	GS-L05	VIA SP & M SERIES M/B
	HP21	GS-L05	VIA CN M/B

PICTURE	NAME	FOR CASE	FOR MAINBOARD
	HP22	GS-L05	VIA EN M/B
	HP24	GS-L06, GS-L07	JETWAY J7F2
	HP25	GS-L06, GS-L07	VIA SP & M SERIES M/B
	HP27	GS-L05	VIA EX M/B
	HP28	GS-L06	VIA EX M/B
	HP29	GA-L01, GD-L01, GS-L01, GS-L02, GS-L02 L	VIA EX & LT M/B
	HP30	GS-L08	VIA EPIA PX M/B

PICTURE	NAME	FOR CASE	FOR MAINBOARD
	HP32	GS-L05	IBASE MB879, MB890 & MB896F M/B; Commell LV-675 & LV-677 M/B; VIA VB6002 M/B (PN)
	HP35	GS-L09	VIA EPIA NX M/B
	HP36	GS-L05	Those M/Bs with hole-to-hole distance for heat device is 41x41mm
	HP37	GS-L06	VIA CN M/B VIA EN M/B
	HP38	GS-L05	VIA EX & LT M/B
	HP39	GS-L06	Those M/Bs with hole-to-hole distance for heat device is 41x41mm

PICTURE	NAME	FOR CASE	FOR MAINBOARD
	HP40	GS-L06	VIA CN & EN M/B
	HP41	GS-L06	VIA EX & LT M/B
	HP45	GA-L01, GD-L01, GS-L01, GS-L02, GS-L02L	VIA EPIA-LN M/B
	HP46	GS-L05	Intel-D201GLY M/B
	HP47	GS-L06	Intel-D201GLY M/B
	HP49	GA-L01	PWI-8552 M/B

PICTURE	NAME	FOR CASE	FOR MAINBOARD
	HP50	GS-L06	Intel D201 GLY M/B
	HP51	GS-L05	Jetway J7F5 M/B
	HP52	GS-L02	Jetway J7F5 M/B (Need to make modification on case structure.)
In Design	HP54	GS-L05	VIA EPIA-LN M/B
	HP55	GS-L05	VIA EPIA-LN M/B
In Design	HP56	GS-L01, GS-L02	VIA SN18000G M/B

PICTURE	NAME	FOR CASE	FOR MAINBOARD
	HP60	GS-L05	Jetway J9F2 M/B
	HP61	GA-L01, GD-L01, GS-L01, GS-L02	Intel D945GCLF M/B
	HP62	GS-L05	Intel D945GCLF M/B
	HP63	GS-L06	Intel D945GCLF M/B
	HP65	GS-L05	Fujitsu Siemens M/B
	HP67	GS-L02	MSI CX700(MS-9802)
	HP68	GW-01	SBS M/B
	HP69	GS-L05	SBS M/B